

MATERIAL DECLARATION



NO	BREAKDOWN OF PART	MANUFACTURER	MATERIAL NAME	CHEMICAL SYMBOL	CAS NO.	%	TOTAL		1.5140	
							WEIGHT	SUBSTANCE MASS. (Mg)	%	SUBSTANCE %
1	Alumina Substrate	Leatec Fine Ceramics	Al2O3 substrate	Al2O3	1344-28-1	96.00	490.00	470.400	13.091	12.5675
				SiO2	14808-60-7	3.00		14.700		0.3927
				MgO	1309-48-4	1.00		4.900		0.1309
2	Resistor Layer	SUMITOMO	Resistive	Silver	744-22-4	30.00	60.00	18.000	1.603	0.4809
				Paste	744-05-3	10.00		6.000		0.1603
				Puthenium Oxide	12036-10-1	10.00		6.000		0.1603
				Lead Oxide	1317-36-8	15.00		9.000		0.2404
				Boron Trioxide	1303-86-2	2.00		1.200		0.0321
				Aluminium Oxide	1344-28-1	2.00		1.200		0.0321
				Silicon Dioxide	7631-86-9	10.00		6.000		0.1603
				Zinc Oxide	1314-13-2	2.00		1.200		0.0321
				Copper Oxide	1317-38-0	0.50		0.300		0.0080
				Manganese Oxide	1317-35-7	1.50		0.900		0.0240
				Tantalum Oxide	1314-61-0	1.50		0.900		0.0240
				Titanium Dioxide	13463-67-7	0.50		0.300		0.0080
				Terpineol	8000-41-7	10.00		6.000		0.1603
Dibutyl Decanedioate	109-43-3	5.00	3.000	0.0801						
3	Flange	HCT	Lead Frame	Cu	7440-50-8	100.00	133.00	133.000	3.553	3.5533
4	Solder	SHENMAO	Lead-free solder	Sn	7440-31-5	94.30	280.00	264.040	7.481	7.0542
				Ag	7440-22-4	3.00		8.400		0.2244
				Cu	7440-50-8	0.50		1.400		0.0347
				Rosin	8050-09-7	2.00		5.600		0.1496
				Activator	Not Established	0.10		0.280		0.0075
				Others	Not Established	0.10		0.280		0.0075
5	Molding	ETERNAL	Epoxy Resin	Crystalline Silica	14808-60-7	72.50	2780.00	2015.500	74.272	53.8472
				Fused Silica	60676-86-0	10.00		278.000		7.4272
				Epoxy Resin	29690-82-2	10.00		278.000		7.4272
				Phenol Resin	9003-35-4	5.00		139.000		3.7136
				Metal hydroxide	-	2.00		55.600		1.4854
				Carbon Black	1333-86-4	0.50		13.900		0.3714

